



Material Composition Declaration

EPC2055

Company Name	Efficient Power Conversion (EPC)	Issue Date:	12/16/2020
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	5.8 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	4.3295	74.3558	76.9428	743558
	Silicon oxide	7631-86-9	0.0154	0.2649		2649
	Silicon nitride	12033-89-5	0.0063	0.1083		1083
	Gallium nitride	25617-97-4	0.0181	0.3116		3116
	Aluminum	7429-90-5	0.0616	1.0587		10587
	Aluminum nitride	24304-00-5	0.0029	0.0503		503
	Titanium	7440-32-6	0.0011	0.0196		196
	Titanium nitride	25583-20-4	0.0059	0.1014		1014
	Copper	7440-50-8	0.0021	0.0352		352
	Tungsten	7440-33-7	0.0023	0.0394		394
	Polyimide		0.0348	0.5977	5977	
Under Bump Metal	Titanium	7440-32-6	0.0007	0.0115	0.1264	115
	Copper	7440-50-8	0.0067	0.1148		1148
Solder Bump	Copper	7440-50-8	0.0669	1.1481	22.9308	11481
	Nickel	7440-02-0	0.0399	0.6849		6849
	Tin	7440-31-5	1.2063	20.7180		207180
	Silver	7440-22-4	0.0221	0.3798		3798
Sum in total:			5.8226	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.